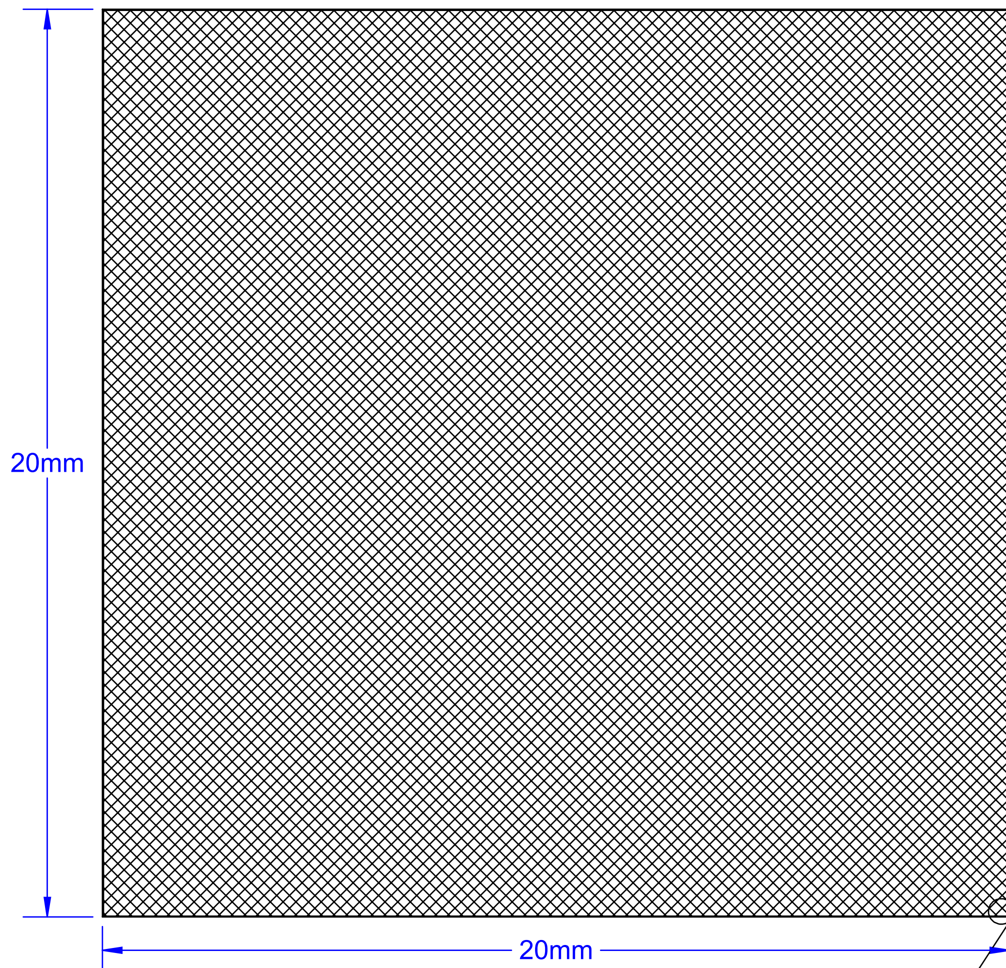
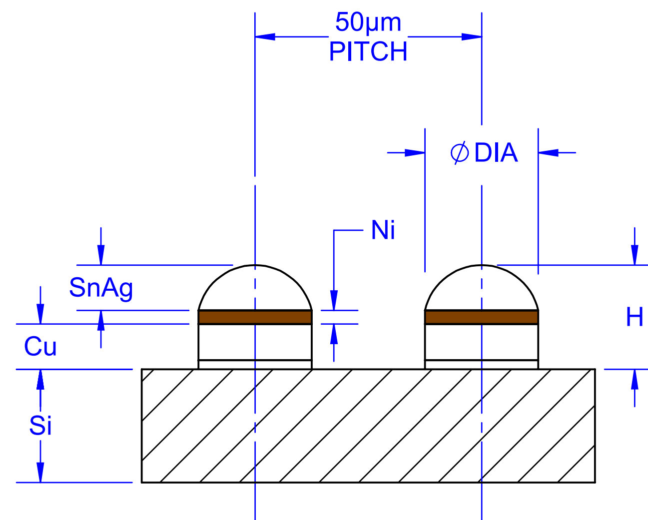
TOP VIEW

BUMP ARRAY 397 x 397



COPPER PILLAR

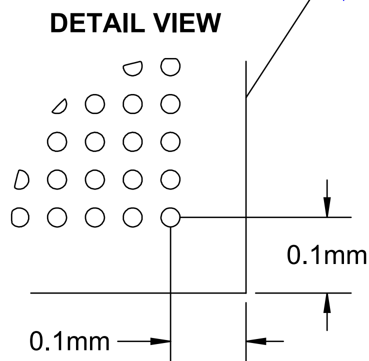


BUMP SECTION VIEW

BUMP DIMENSIONS TABLE		
H	BUMP HEIGHT	23µm
SnAg	SOLDER CAP	10µm
Ni	NICKEL	3µm
Cu	COPPER	10µm
∅	DIAMETER	25µm
PITCH	BUMP PITCH	50µm

SOLDER CAP MATERIAL: Sn98.2 Ag1.8

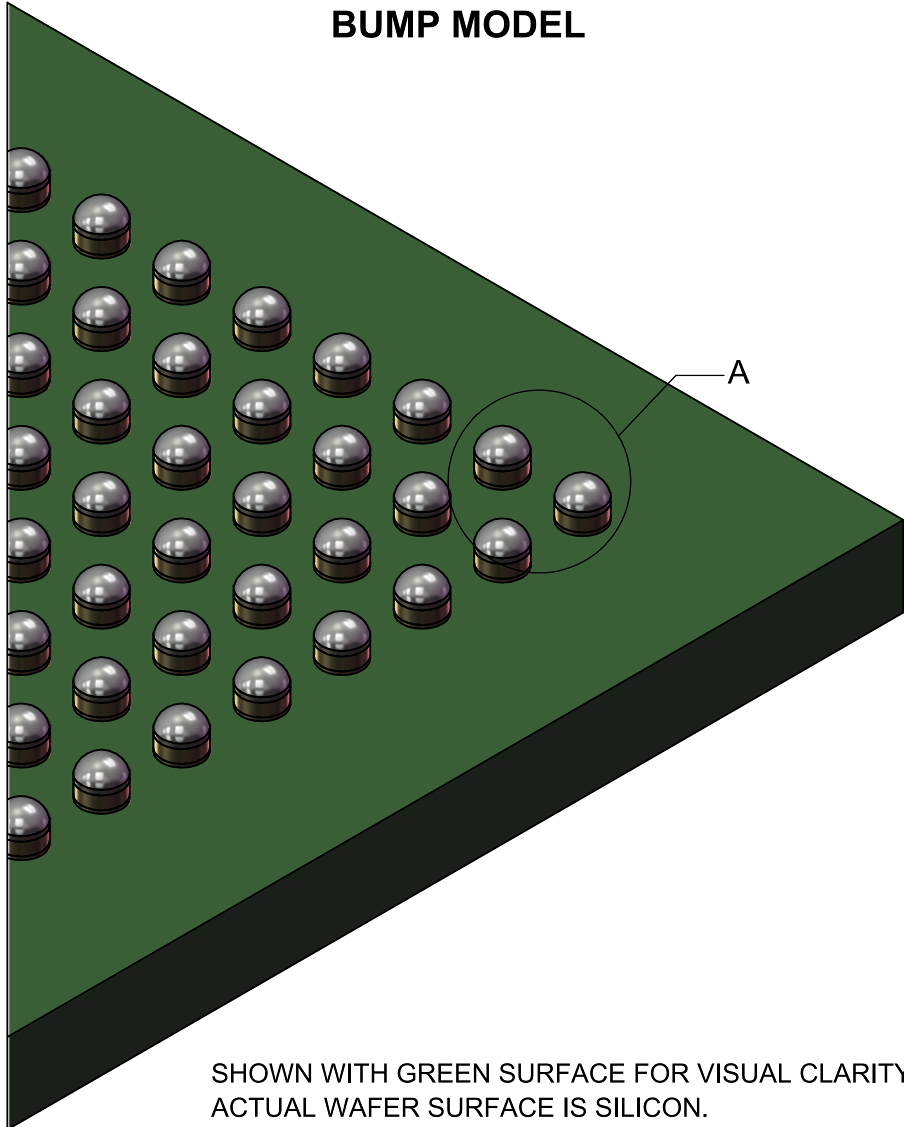
DETAIL VIEW

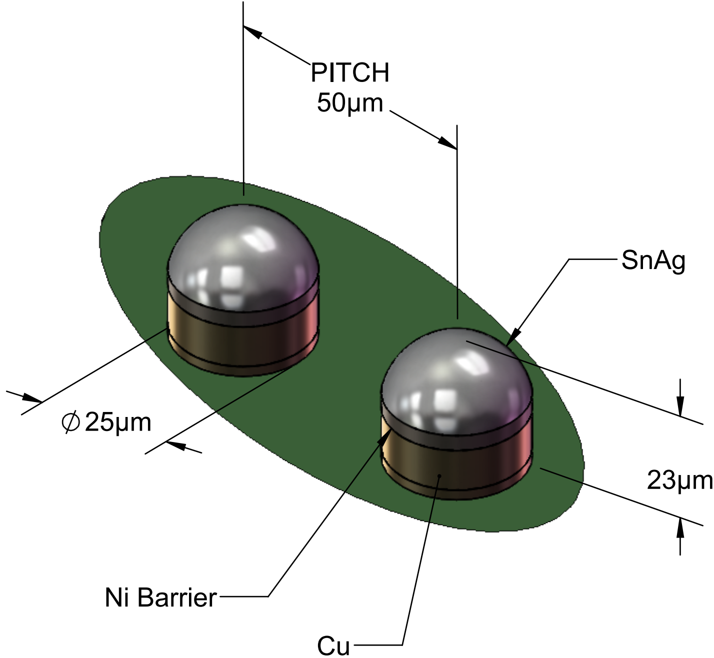


WAFER 200mm (8-INCH)
DICING STREET 20 x 20mm
DIE SIZE AFTER DICING ~19.96 x 19.96mm
BUMPS ~157,609 - YIELD NOT 100%

APPROVALS		DATE	
DRAWN	T.Au	6/18/2021	TopLine®
ENG	M. Hart	6/18/2021	TITLE: FC157K - PITCH 50UM CU PILLAR 20X20MM
MFG			
QA			SCALE 6:1 / SIZE A / DRAWING NO. 353970 / REV A
CUST			
REVISED			DO NOT SCALE DRAWING / SHEET 1 OF 3

BUMP MODEL





DETAIL A
SCALE 800 : 1

SHOWN WITH GREEN SURFACE FOR VISUAL CLARITY.
ACTUAL WAFER SURFACE IS SILICON.

TopLine®			
TITLE	FC157K- PITCH 50UM CU PILLAR 20X20MM		
SCALE 300:1	SIZE A	DRAWING NO. 353970	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 3	

FC 157K 20 C 50 - OPTION - I - G

FLIP CHIP

FC = FLIP CHIP (DICED)
FCWN = UNSAWN 8" WAFER

BUMPS

CODE	BUMPS	ARRAY
157K	157609	397 x 397

DIE SIZE

CODE	MM
20	20 X 20mm

BUMP MATERIAL

Cu PILLAR

MATL	HEIGHT
Sn98.2 Ag1.8	10µm
Ni	3µm
Cu	10µm

PITCH

50 = 50µm

THICKNESS

CODE	µm	MIL
NONE	725µm	28.5 MIL
BG500	500µm	20 MIL
BG400	400µm	16 MIL
BG375	375µm	15 MIL
BG300	300µm	12 MIL
BG250	250µm	10 MIL
BG200	200µm	8 MIL
BG150	150µm	6 MIL
BG100	100µm	4 MIL

OTHER THICKNESS AVAILABLE

* CIRCUIT

I = ISOLATED
BUS = ALL SHORTED

PACKAGING

G = GEL PAK (4 pcs)
P = 4" CHIP TRAY (9 pcs)
UV = UV TAPE 8" RING (52 pcs)
C= WAFER CASSETTE (52pcs)

OTHER AVAILABLE

*** CIRCUIT NOTES:**

ISOLATED = SiO_2 STANDARD
BUS = WAFER PROBE ONLY

TITLE	FC157K - PITCH 50UM CU PILLAR 20X20MM		
SCALE	SIZE	DRAWING NO.	REV
NONE	A	353970	A
DO NOT SCALE DRAWING			SHEET 3 OF 3